

SB&SPB Code Information(1/2)

Last Updated : November 2008

K 7 X X X X X X X X - X X X X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. Sync(SB&SPB) SRAM : 7

3. Small Classification

A : Sync Pipelined Burst

B : Sync Burst

4~5. Density

20 : 2M 40 : 4M 80 : 8M
 16 : 16M 32 : 32M 64 : 64M

6~7. Organization

18 : x18 32 : x32 36 : x36

8~9. Vcc, Interface, Mode

00 : 3.3V, LVTTTL, 2E1D WIDE
 01 : 3.3V, LVTTTL, 2E2D WIDE
 09 : 3.3V, LVTTTL, Hi SPEED
 25 : 3.3V, LVTTTL, SB-FT WIDE
 30 : 2.5/ 3.3V, LVTTTL, 2E1D
 31 : 2.5/ 3.3V, LVTTTL, 2E2D
 35 : 2.5/ 3.3V, LVTTTL, SB-FT

10. Generation

M : 1st Generation
 A : 2nd Generation
 B : 3rd Generation
 C : 4th Generation

11. "—"

12. Package

P : (T)QFP (Lead-Free) Q : (T)QFP
 C : CHIP BIZ W : WAFER

13. Temp, Power

- COMMON (Temp, Power)

C : Commercial, Normal
 I : Industrial, Normal

- WAFER, CHIP BIZ Level Division

0 : NONE, NONE
 1 : Hot DC sort
 2 : Hot DC, selected AC sort

14~15. Speed

- Sync Burst, Sync Burst

65 : 6.5ns 75 : 7.5ns
 80 : 8ns 85 : 8.5ns

- Other Small Classification (Clock Cycle Time)

10 : 100MHz 11 : 117MHz
 14 : 138MHz 16 : 166MHz
 20 : 200MHz 25 : 250MHz

SB&SPB Code Information(2/2)

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16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

| Divide | Packing Type | New Marking |
|-----------------------------------|---------------------------|-------------|
| Component | TAPE & REEL | T |
| | Other (Tray, Tube, Jar) | 0 (Number) |
| | Stack | S |
| Component (Mask ROM) | TRAY | Y |
| | AMMO PACKING | A |
| Module | MODULE TAPE & REEL | P |
| | MODULE Other Packing | M |

17~18. Customer "Customer List Reference"